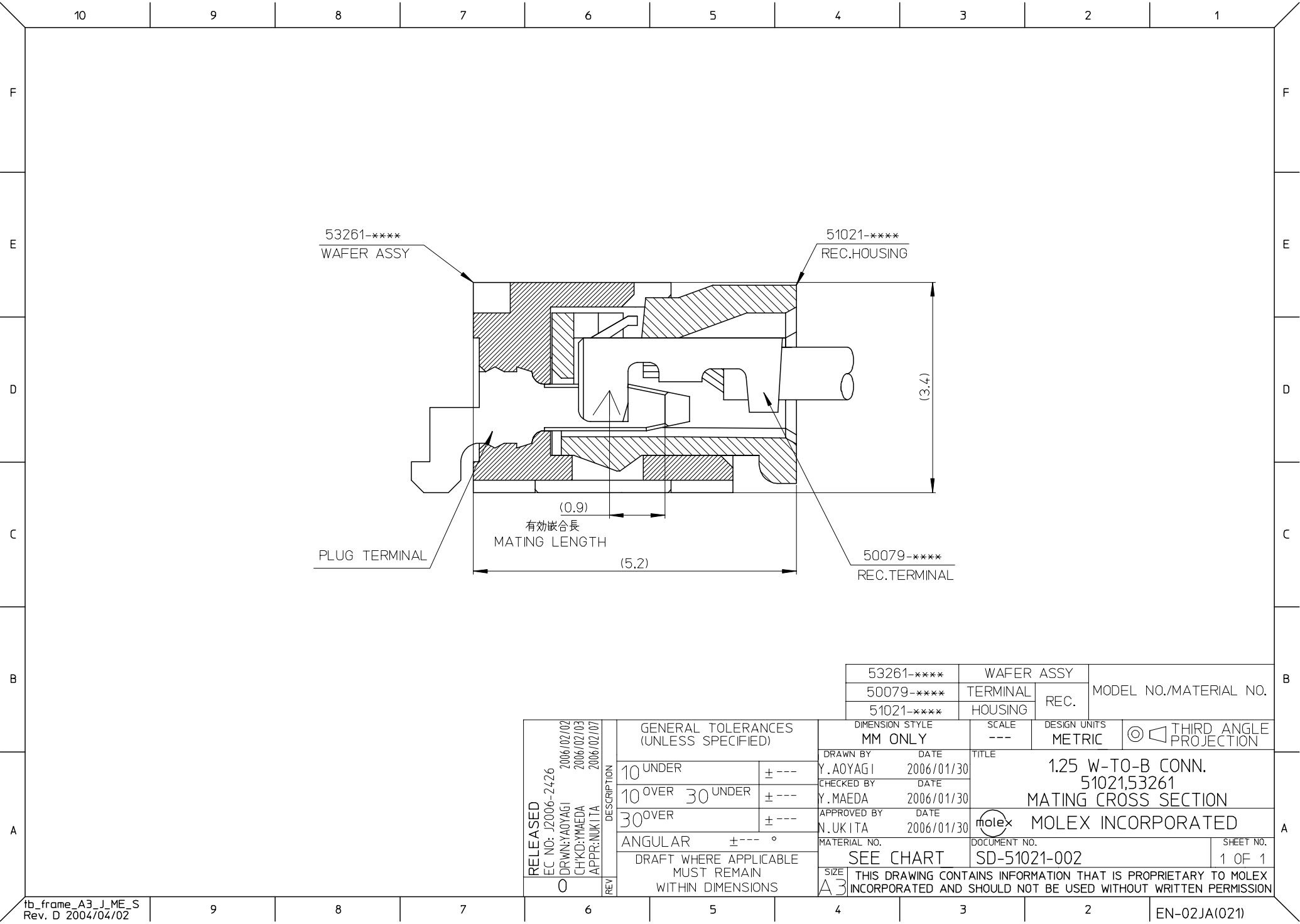
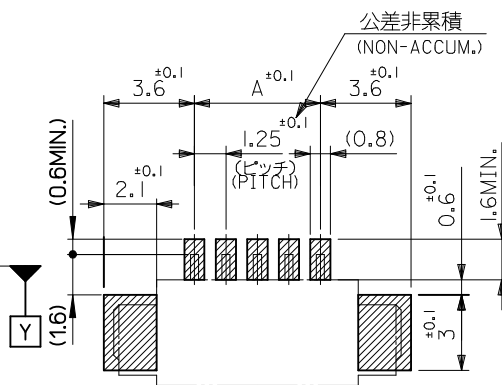




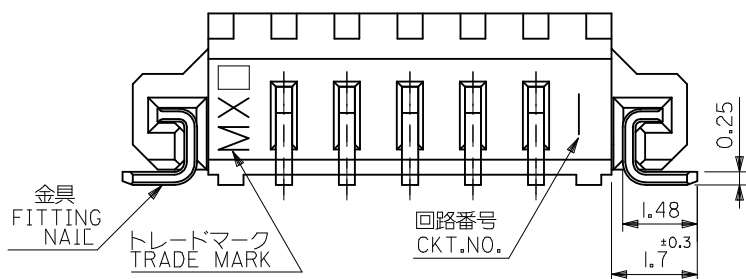
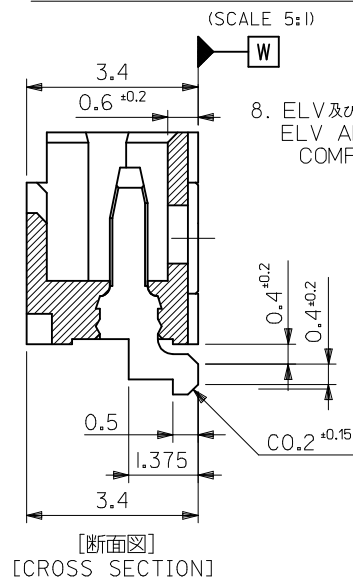
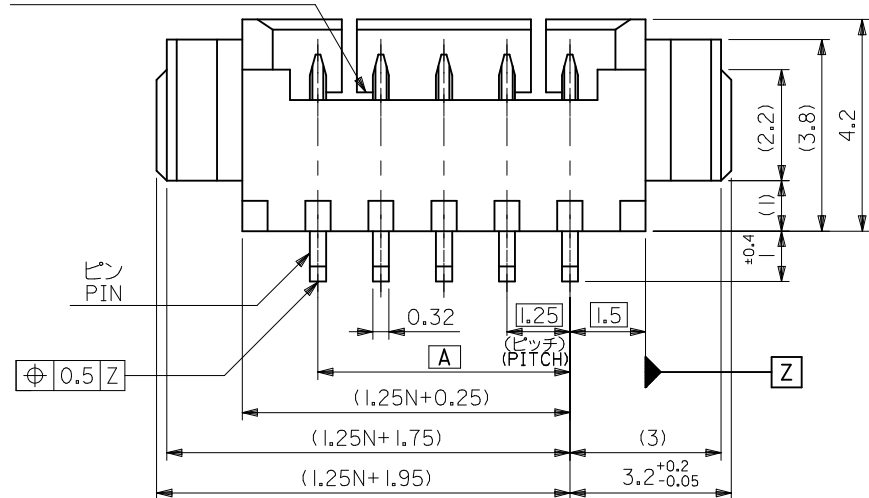
53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: YAOYAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07 REV 0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY Y. AOYAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
		10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30					
		30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.			DOCUMENT NO.			SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART			SD-51021-002			1 OF 1
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



注記 NOTES

1. 嵌合相手： 5 I02 I シリーズ
MATES WITH: 5 I02 I SERIES
2. 材質
MATERIAL
ウエハー： NYLON 46, UL 94V-0 GLASS FILLED 30%
COLOR BLACK
- ピン：リン青銅
PIN：PHOSPHOR BRONZE
- 金具：リン青銅
FITTING NAIL：PHOSPHOR BRONZE
3. メッキ仕様 ピン：錫メッキ 1.0 μ mMIN.
PLATING PIN：TIN 1.0 MICROMETER MIN.
下地メッキ：ニッケルメッキ 1.0 μ mMIN.
UNDER-PLATING:NICKEL 1.0 MICROMETER MIN.
金具：錫メッキ 1.0 μ mMIN.
FITTING NAIL:TIN 1.0 MICROMETER MIN.
下地メッキ：ニッケルメッキ 1.0 μ mMIN.
UNDER-PLATING:NICKEL 1.0 MICROMETER MIN.
4. ソルダーテール部のズレ量及び金具（補強板）のズレ量は基準面
[W] に対し、上方向 0.05MAX.、下方向に 0.1 MAX. とする。
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL
BOTTOM AND FITTING NAIL BOTTOM：
UPPER SIDE：0.05MAX.
LOWER SIDE：0.1MAX.
- △ ロック窓は 2、3 極は 1 箇所、4 極以上は 2 箇所とする。
LOCK WINDOW：ONE PLACE FOR 2 AND 3
CKTS. AND TWO PLACES
FOR MORE THAN 3 CKTS.
6. 本製品は 53261-**-11、**-68 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-11, **-68.
7. ソルダーテール及び金具の平坦度は 0.1 以下。
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.



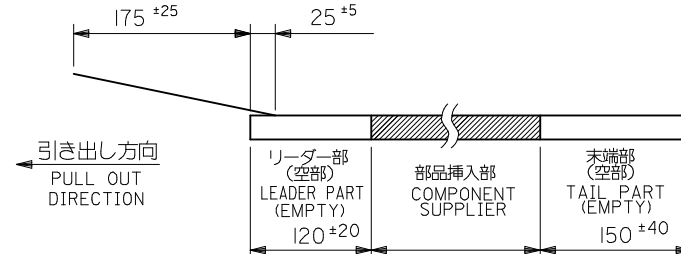
22.65	22.25	19.25	18.05	16.25	53261-1417	14
20.15	19.75	16.75	15.55	13.75	53261-1217	12
16.4	16	13	11.8	10	53261-0917	9
15.15	14.75	11.75	10.55	8.75	53261-0817	8
13.9	13.5	10.5	9.3	7.5	53261-0717	7
12.65	12.25	9.25	8.05	6.25	53261-0617	6
11.4	11	8	6.8	5	53261-0517	5
10.15	9.75	6.75	5.55	3.75	53261-0417	4
8.9	8.5	5.5	4.3	2.5	53261-0317	3
7.65	7.25	4.25	3.05	1.25	53261-0217	2
E	D	C	B	A	MATERIAL NO.	CKT.

REVISED EC NO.: J2016-1122 DRWN:GHE31 CHKD:SAKIYAMA APPR:TRANEKO	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT R/A	molex	DOCUMENT NO. SD-53261-025	SHEET NO. 1 OF 1
		0.25 OVER	0.5 UNDER	±0.05	YWADA	04/04/12				
		0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE				
		1.0 OVER	10 UNDER	±0.2	MSASAO	04/04/12	APPROVED BY	DATE	MSASAO	04/04/12
		10 OVER	30 UNDER	±0.25						
		30 OVER		±0.3	MATERIAL NO.					
		ANGULAR	±3 °	SEE CHART						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

注記
 NOTES

1. 53261-**-17 の詳細寸法については図面 SD-53261-025 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-025
2. 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH

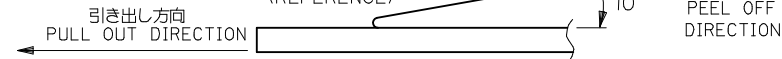
トップテープリーダー部 トップテープ未接着部
TOP TAPE LEADER PART TOP TAPE NON-BONDED PART



4. トップテープの剥離強度: 0.1~1.3N{10~130gf} (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.1~1.3N{10~130gf}
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)

<剥離速度： 300mm/min (参考)>

PEELING SPEED:300mm/min.
(REFERENCE)



5. 材料 (MATERIAL)
 キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
 トップテープ (TOP TAPE): PET ,PE ,PEF
 リール (REEL): ポリスチレン (PS) <リサイクル材含む>
 POLYSTYRENE(PS)<RECYCLE MATERIAL CONTAINED>

△6 コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA

7. 本製品は53261-**-95, -**-98の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-95, -**-98.
8. 本製品は乾燥剤入り、ハイバリア梱包品である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16	21.4	17.4	2.45	8.25	53261-0227	2
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	極数 CKT.

MODEL NO.	53261-**27
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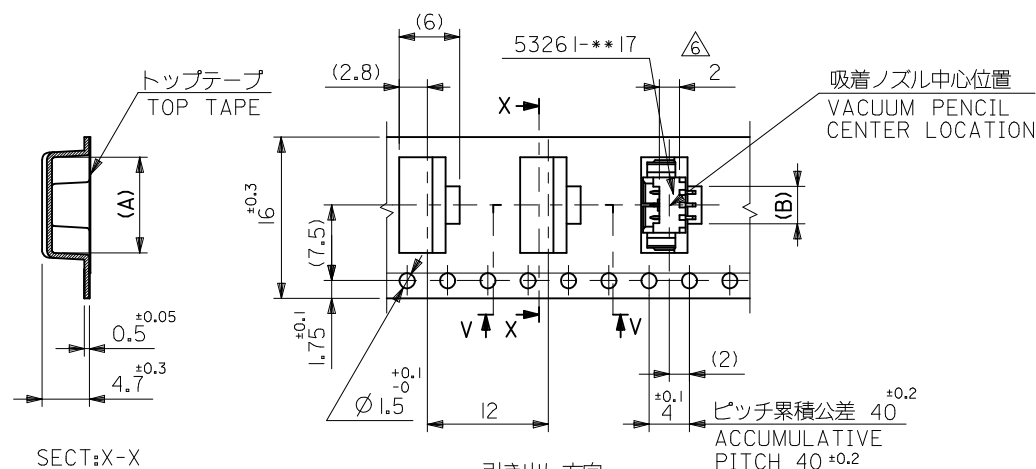
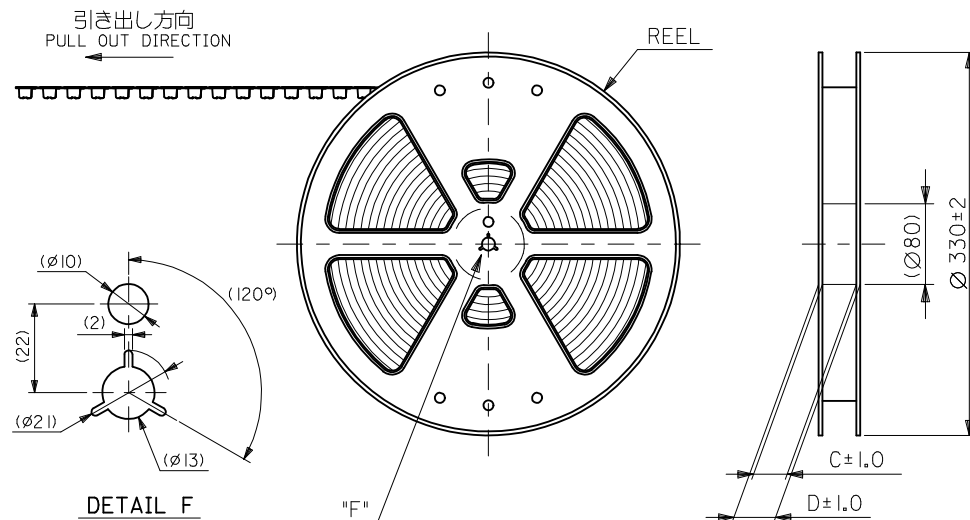
DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
-------------------------------	---

1.25 W/B CONN. WAFER
ASSY SMT EMBSTP PKG
-LEAD FREE-

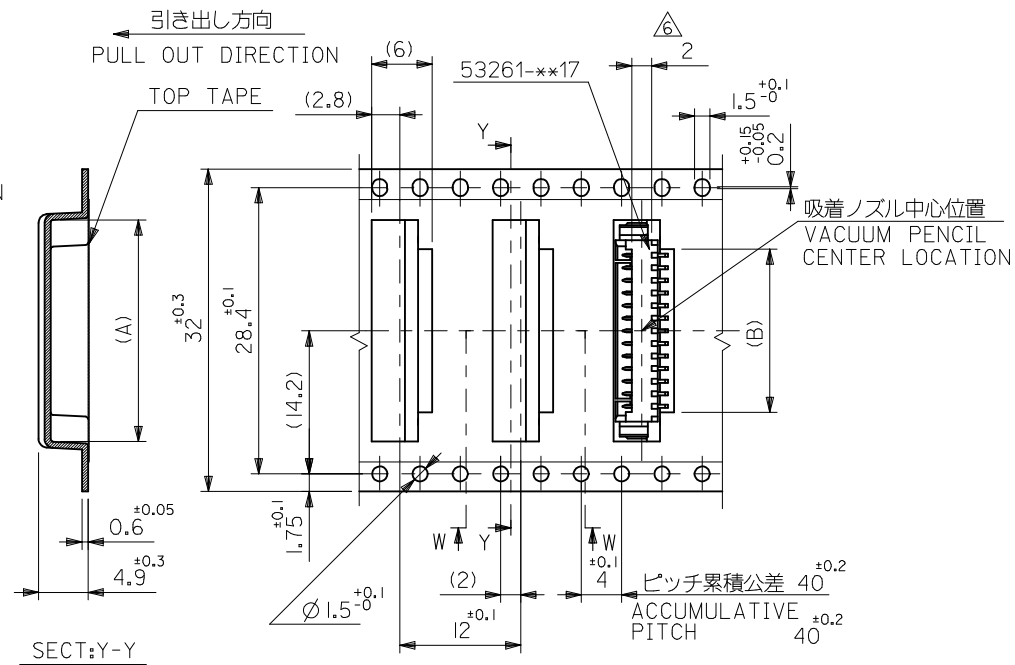
2  MOLEX INCORPORATED

SERIAL NO. SEE CHART	DOCUMENT NO. SD-53261-026
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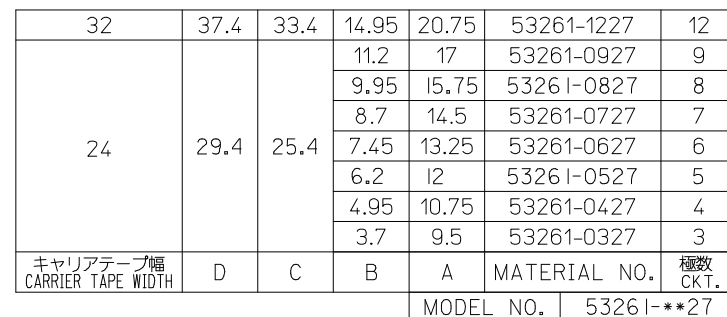
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



REVISED	
EC NO: J2009-2060	2009/05/20
DRWN:TKON	2009/05/21
CH'KD:HIMATSUMOTO	2009/05/21
APPR:NUKITA	2009/05/21



32 mm幅キャリアテープ

EN-02JA(021)

10

9

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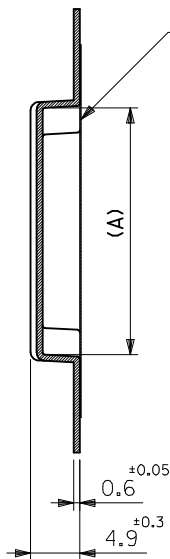
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2

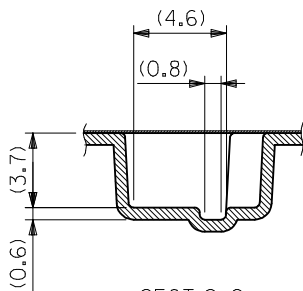
1

引き出し方向
PULL OUT DIRECTION

トップテープ
TOP TAPE

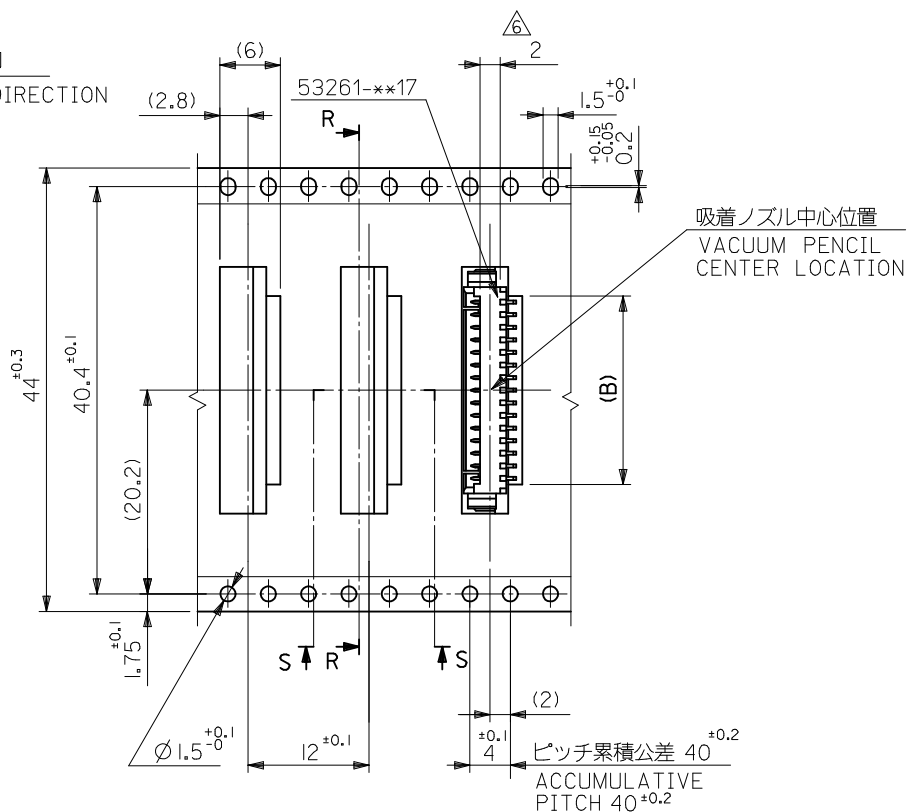


SECT:R-R



SECT:S-S

44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE



44	49.5	45.4	17.45	23.25	53261-1427	14
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	極数 CKT.

MODEL NO. 53261-**27

REVISED EC NO: J2009-2060 DRWN:TKON 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21 D	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION
		10 UNDER	± 0.2	DRAWN BY Y. WADA	DATE '04/04/12	TITLE 1.25 W/B CONN. WAFER ASSY SMT EMBSTP PKG -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE '04/04/12				
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/04/12	 MOLEX INCORPORATED			
		ANGULAR ±3 °		MATERIAL NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53261-026		3 OF 3	
	REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9

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2

Mouser Electronics

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